



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Hideki Tanaka

Serial No.: 09/788,503

Group Art Unit: 2823

Filed: February 21, 2001

Examiner: Nguyen, Khiem D.

For: TAPE CARRIER TYPE SEMICONDUCTOR DEVICE, METHOD FOR
MANUFACTURING THE SAME, AND FLEXIBLE SUBSTRATE

Honorable Commissioner of Patents
Washington, D.C. 20231

Fee OK

1-17-03
L. Spruill

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AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated **October 8, 2002**, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claim 12 without prejudice or disclaimer.

Please amend the following claims:

1. (Amended) A tape carrier type semiconductor device comprising:

a flexible substrate on whose surface wiring is formed; and

a driver circuit which is mounted on said flexible substrate and drives a device connected to said flexible substrate,

wherein said flexible substrate includes a first slit having a connector situated intermediate thereto for connecting both sides of the first slit to reduce warpage, and

wherein said first slit comprises a first sub-slit and a second sub-slit with said connector therebetween.

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